

1. (Amended) An electronic circuit unit comprising thin film circuit elements including capacitors, resistors, and inductance elements formed on an alumina substrate, and a semiconductor bare chip having a first transistor wire bonded to the alumina substrate, wherein only an emitter resistor, out of base bias voltage dividing resistors and the emitter resistor of the first transistor, is trimmed to set a current value of the first transistor.

7. (New) The electronic circuit unit of claim 1, wherein the emitter resistor is formed more distal to the first transistor than the base bias voltage dividing resistors.

8. (New) The electronic circuit unit of claim 1, wherein the resistors are formed in the same thin film forming technique.

9. (New) The electronic circuit unit of claim 3, wherein the base bias voltage dividing resistors are formed more proximate to the first transistor than an emitter resistor of the first transistor.

10. (New) The electronic circuit unit of claim 3, wherein the resistors are formed in the same thin film technique.

11. (New) The electronic circuit unit of claim 3, wherein out of the base bias voltage dividing resistors and an emitter resistor of the first transistor, only the emitter resistor is trimmed to set a current value of the first transistor.

Remarks

Summary

Claims 1-6 were pending. Claims 7-11 have been added and Claim 1 have been amended. No new matter has been added as a result of this amendment. Claims pending after entry of this amendment are Claims 1-11.

Objection to Claims

In the Office Action, Claims 1 and 3 were objected to for informalities. The Examiner stated that correction was required to change the element, "a semiconductor bare chip having a first transistor wire bonded to the alumina